Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L4	1796	(plastic\$4 flexib\$6 organic resin polymer\$6) near3 (substrate back\$plate back\$panel face\$plate face\$panel front\$plate rear\$plate rear\$panel panel plate) with (thinning thining thinned thined blast\$4 sand\$blast\$3 abrad\$4 abrat\$3 ablat\$4 grind\$4 etch\$4 reduc\$4 heat\$4 bak\$4 shrink\$4 polish\$4 rough\$4 scratch\$4 smooth\$4) with (manufactur\$4 process\$4 method\$6 procedur\$4 step) and (LED.U/C. OLED.U/C. OELD.U/C. (electro\$1luminescen\$ near (display device panel diode)) ((light photo photon) near (emitting emission emissive) near (device diode display panel)))	US-PGPUB; USPAT; USOCR	OR	ON	2006/07/28 14:00
S58	2383	(plastic\$4 flexib\$6 organic resin polymer\$6) near3 (substrate back\$plate back\$panel face\$plate face\$panel front\$plate rear\$plate rear\$plate rear\$plate panel plate) with (thin\$4 blast\$4 sand\$blast\$3 abrad\$4 abrat\$3 ablat\$4 grind\$4 etch\$4 reduc\$4 heat\$4 bak\$4 shrink\$4 polish\$4 rough\$4 scratch\$4 smooth\$4) with (manufactur\$4 process\$4 method\$6 procedur\$4 step) and (LED.U/C. OLED.U/C. OELD.U/C. (electro\$1luminescen\$ near (display device panel diode)) ((light photo photon) near (emitting emission emissive) near (device diode display panel)))	US-PGPUB; USPAT; USOCR	OR	ON	2006/07/28 13:59

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L3	360	(plastic\$4 flexib\$6 organic resin polymer\$6) near3 (substrate back\$plate back\$panel face\$plate face\$panel front\$plate rear\$plate rear\$panel panel plate) with (thin\$4 blast\$4 sand\$blast\$3 abrad\$4 abrat\$3 ablat\$4 grind\$4 etch\$4 reduc\$4 heat\$4 bak\$4 shrink\$4 polish\$4 rough\$4 scratch\$4 smooth\$4) with (manufactur\$4 process\$4 method\$6 procedur\$4 step) and (LED.U/C. OLED.U/C. OELD.U/C. (electro\$1luminescen\$ near3 (display device panel diode member structure)) ((light photo photon) near3 (emitting emission emissive) near3 (device diode display panel member structure)))	EPO; JPO; DERWENT	OR	ON	2006/07/28 13:58
L1	303	(plastic\$4 flexib\$6 organic resin polymer\$6) near3 (substrate back\$plate back\$panel face\$plate face\$panel front\$plate rear\$plate rear\$panel panel plate) with (thin\$4 blast\$4 sand\$blast\$3 abrad\$4 abrat\$3 ablat\$4 grind\$4 etch\$4 reduc\$4 heat\$4 bak\$4 shrink\$4 polish\$4 rough\$4 scratch\$4 smooth\$4) with (manufactur\$4 process\$4 method\$6 procedur\$4 step) and (LED.U/C. OLED.U/C. OELD.U/C. (electro\$1luminescen\$ near (display device panel diode)) ((light photo photon) near (emitting emission emissive) near (device diode display panel)))	EPO; JPO; DERWENT	OR	ON	2006/07/28 13:57
L2	304	(plastic\$4 flexib\$6 organic resin polymer\$6) near3 (substrate back\$plate back\$panel face\$plate face\$panel front\$panel front\$plate rear\$plate rear\$panel panel plate) with (thin\$4 blast\$4 sand\$blast\$3 abrad\$4 abrat\$3 ablat\$4 grind\$4 etch\$4 reduc\$4 heat\$4 bak\$4 shrink\$4 polish\$4 rough\$4 scratch\$4 smooth\$4) with (manufactur\$4 process\$4 method\$6 procedur\$4 step) and (LED.U/C. OLED.U/C. OELD.U/C. (electro\$1luminescen\$ near (display device panel diode member structure)) ((light photo photon) near (emitting emission emissive) near (device diode display panel member structure)))	EPO; JPO; DERWENT	OR	ON	2006/07/28 13:57

S57	2770	(plastic\$4 flexib\$6 organic resin polymer\$6) near3 (substrate back\$plate back\$panel face\$plate face\$panel front\$panel front\$plate rear\$plate rear\$plate rear\$plate yand\$1 plate) with (thin\$4 blast\$4 sand\$blast\$3 abrad\$4 abrat\$3 ablat\$4 grind\$4 etch\$4 reduc\$4 heat\$4 bak\$4 shrink\$4 polish\$4 rough\$4 scratch\$4 smooth\$4) with (manufactur\$4 process\$4 method\$6 procedur\$4 step) and (LED.U/C. OLED.U/C. OELD.U/C. electro\$1luminescen\$1 lumines\$6 ((light photo photon) near (emitting emission emissive) near (device diode display panel)))	US-PGPUB; USPAT; USOCR	OR	ON	2006/07/27 09:43
S56	2849	(plastic\$4 flexib\$6 organic resin polymer\$6) near3 (substrate back\$plate back\$panel face\$plate face\$panel front\$panel front\$plate rear\$plate rear\$plate rear\$plate rear\$plate sand\$blast\$3 abrad\$4 abrat\$3 ablat\$4 grind\$4 etch\$4 reduc\$4 heat\$4 bak\$4 shrink\$4 polish\$4 rough\$4 scratch\$4 smooth\$4) with (manufactur\$4 process\$4 method\$6 procedur\$4 step) and (LED.U/C. OLED.U/C. OELD.U/C. electro\$1luminescen\$ lumines\$6 ((light photo photon) near3 (emitting emission emissive) near3 (device diode display panel)))	US-PGPUB; USPAT; USOCR	OR	ON	2006/07/27 09:42
S55	3318	(plastic\$4 flexib\$6 organic resin polymer\$6) near3 (substrate back\$plate back\$panel face\$plate face\$panel front\$panel front\$plate rear\$plate rear\$plate rear\$panel panel plate) with (thin\$4 blast\$4 sand\$blast\$3 abrad\$4 abrat\$3 ablat\$4 grind\$4 etch\$4 reduc\$4 heat\$4 bak\$4 shrink\$4 polish\$4 rough\$4 scratch\$4 smooth\$4) with (manufactur\$4 process\$4 method\$6 procedur\$4 step) and (LED.U/C. OLED.U/C. OELD.U/C. electro\$1luminescen\$ lumines\$6 ((light photo photon) near3 (emitting emission emissive))))	US-PGPUB; USPAT; USOCR	OR	ON	2006/07/27 09:41

S54	6796	(plastic\$4 flexib\$6 organic resin polymer\$6) with (substrate back\$plate back\$panel face\$plate face\$plate face\$panel front\$panel front\$plate rear\$plate rear\$panel panel plate) with (thin\$4 blast\$4 sand\$blast\$3 abrad\$4 abrat\$3 ablat\$4 grind\$4 etch\$4 reduc\$4 heat\$4 bak\$4 shrink\$4 polish\$4 rough\$4 scratch\$4 smooth\$4) with (manufactur\$4 process\$4 method\$6 procedur\$4 step) and (LED.U/C. OLED.U/C. OELD.U/C. electro\$1luminescen\$ lumines\$6 ((light photo photon) near3 (emitting emission emissive)))	US-PGPUB; USPAT; USOCR	OR	ON	2006/07/27 09:40
S46	1467	(plastic\$4 flexib\$6 organic resin polymer\$6) same (substrate back\$plate back\$panel face\$plate face\$panel front\$panel front\$plate rear\$plate rear\$panel panel plate) with (thin\$4 blast\$4 sand\$blast\$3 abrad\$4 abrat\$3 ablat\$4 grind\$4 etch\$4 reduc\$4 heat\$4 bak\$4 shrink\$4 polish\$4 rough\$4 scratch\$4 smooth\$4) with (manufactur\$4 process\$4 method\$6 procedur\$4 step) and (LED.U/C. OLED.U/C. OELD.U/C. electro\$1luminescen\$ lumines\$6 ((light photo photon) near3 (emitting emission emissive)))	EPO; JPO; DERWENT	OR	ON	2006/07/27 09:36
S47	10178	(plastic\$4 flexib\$6 organic resin polymer\$6) same (substrate back\$plate back\$panel face\$plate face\$panel front\$panel front\$plate rear\$plate rear\$plate panel plate) with (thin\$4 blast\$4 sand\$blast\$3 abrad\$4 abrat\$3 ablat\$4 grind\$4 etch\$4 reduc\$4 heat\$4 bak\$4 shrink\$4 polish\$4 rough\$4 scratch\$4 smooth\$4) with (manufactur\$4 process\$4 method\$6 procedur\$4 step) and (LED.U/C. OLED.U/C. OELD.U/C. electro\$1luminescen\$ lumines\$6 ((light photo photon) near3 (emitting emission emissive)))	US-PGPUB; USPAT; USOCR	OR	ON	2006/07/27 09:36
S48	580	(156/154).CCLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/07/27 09:33
S49	716	(156/153).CCLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/07/27 09:33

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S50	580	(156/154).CCLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/07/27 09:33
S51	1092	(156/155).CCLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/07/27 09:33
S52	1716	(156/344).CCLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/07/27 09:33
S53	2066	(156/247).CCLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/07/27 09:33
S38	129	(plastic\$4 flexib\$6) same (substrate panel plate) with (thin\$4 blast\$4 sand\$blast\$3 abrad\$4 abrat\$3 ablat\$4 grind\$4 etch\$4 reduc\$4 heat\$4 bak\$4 shrink\$4 polish\$4 rough\$4 scratch\$4 smooth\$4) with (manufactur\$4 process\$4 method\$6 procedur\$4 step) and (LED.U/C. OLED.U/C. OELD.U/C. electro\$1luminescen\$ lumines\$6 ((light photo photon) near3 (emitting emission emissive)))	EPO; JPO; DERWENT	OR	ON	2006/07/27 09:32
S44	1	(manufactur\$4 process\$4 method\$6 procedur\$4 step) same substrate with functional near switch\$4 with bond\$4 same coat\$4 with flexible with polymer with surface	US-PGPUB; USPAT; USOCR	OR	ON	2006/07/17 13:23
S45	1	(manufactur\$4 process\$4 method\$6 procedur\$4 step) same substrate with functional near switch\$4 with bond\$4 same coat\$4 with flexible with polymer with surface	US-PGPUB	OR	ON	2006/07/17 13:23
S37	1739	(plastic\$4 flexib\$6 organic resin polymer\$6) same (substrate panel plate) with (thin\$4 blast\$4 sand\$blast\$3 abrad\$4 abrat\$3 ablat\$4 grind\$4 etch\$4 reduc\$4 heat\$4 bak\$4 shrink\$4 polish\$4 rough\$4 scratch\$4 smooth\$4) same (manufactur\$4 process\$4 method\$6 procedur\$4 step) and (LED.U/C. OLED.U/C. OELD.U/C. electro\$1luminescen\$ lumines\$6 ((light photo photon) near3 (emitting emission emissive)))	EPO; JPO; DERWENT	OR	ON	2006/07/17 13:14
S42	82	(Jung\$Fang near Chang) (Chich\$Shang near Chang) (Chi\$Lin near Chen)	US-PGPUB; USPAT; USOCR	OR	ON	2006/07/17 13:14

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S43	16625	(plastic\$4 flexib\$6 organic resin polymer\$6) same (substrate panel plate) with (thin\$4 blast\$4 sand\$blast\$3 abrad\$4 abrat\$3 ablat\$4 grind\$4 etch\$4 reduc\$4 heat\$4 bak\$4 shrink\$4 polish\$4 rough\$4 scratch\$4 smooth\$4) same (manufactur\$4 process\$4 method\$6 procedur\$4 step) and (LED.U/C. OLED.U/C. OELD.U/C. electro\$1luminescen\$ lumines\$6 ((light photo photon) near3 (emitting emission emissive)))	US-PGPUB; USPAT; USOCR	OR	ON	2006/07/17 13:14		
S41	28	(Jung\$1Fang near Chang) (Chich\$1Shang near Chang) (Chi\$1Lin near Chen)	US-PGPUB; USPAT; USOCR	OR	ON	2006/07/17 13:13		
S40	1462	(plastic\$4 flexib\$6 organic resin polymer\$6) same (substrate panel plate) with (thin\$4 blast\$4 sand\$blast\$3 abrad\$4 abrat\$3 ablat\$4 grind\$4 etch\$4 reduc\$4 heat\$4 bak\$4 shrink\$4 polish\$4 rough\$4 scratch\$4 smooth\$4) with (manufactur\$4 process\$4 method\$6 procedur\$4 step) and (LED.U/C. OLED.U/C. OELD.U/C. electro\$1luminescen\$ lumines\$6 ((light photo photon) near3 (emitting emission emissive)))	EPO; JPO; DERWENT	OR	ON	2006/07/17 13:12		
S39	239236	(plastic\$4 flexib\$6 organic resin polymer\$6) same (substrate panel plate) with (thin\$4 blast\$4 sand\$blast\$3 abrad\$4 abrat\$3 ablat\$4 grind\$4 etch\$4 reduc\$4 heat\$4 bak\$4 shrink\$4 polish\$4 rough\$4 scratch\$4 smooth\$4) with3 (manufactur\$4 process\$4 method\$6 procedur\$4 step) and (LED.U/C. OLED.U/C. OELD.U/C. electro\$1luminescen\$ lumines\$6 ((light photo photon) near3 (emitting emission emissive)))	EPO; JPO; DERWENT	OR	ON	2006/07/17 13:10		
S36	50162	(plastic\$4 flexib\$6 organic resin polymer\$6) same (substrate panel plate) same (manufactur\$4 process\$4 method\$6 procedur\$4 step) same (thin\$4 blast\$4 sand\$blast\$3 abrad\$4 abrat\$3 ablat\$4 grind\$4 etch\$4 reduc\$4 heat\$4 bak\$4 shrink\$4 polish\$4 rough\$4 scratch\$4 smooth\$4)	EPO; JPO; DERWENT	OR	ON	2006/07/17 13:09		

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S35	127136	(plastic\$4 flexib\$6 organic resin polymer\$6) same (substrate panel plate) same (manufactur\$4 process\$4 method\$6 procedur\$4 step)	EPO; JPO; DERWENT	OR	ON	2006/07/17 13:06
S34	436790	(plastic\$4 flexib\$6 organic resin polymer\$6) same (substrate panel plate) same (manufactur\$4 process\$4 method\$6 procedur\$4 step)	US-PGPUB; USPAT; USOCR	OR	ON	2006/07/17 13:05
S19	917358	(plastic\$4 flexib\$6 organic resin polymer\$6) same (substrate panel plate)	US-PGPUB; USPAT; USOCR	OR	ON	2006/07/17 13:03
S5	2498	(445/23-25).CCLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/07/17 13:02
S32	2663	(445/23-25).CCLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/07/17 13:02
S33	583	(445/25).CCLS.	US-PGPUB; USPAT; USOCR	OR	OFF	2006/07/17 13:02